ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

25-JUN-2003

SUBJECT: ON Semiconductor Final Product/Process Change Notification #12511

TITLE: Wafer Capacity Expansion for Selected 50V Analog Products in ON Semiconductor's Czech Republic facility

EFFECTIVE DATE: 25-Aug-2003

AFFECTED CHANGE CATEGORY: ON Semiconductor Fab Site

AFFECTED PRODUCT DIVISION: Analog Products Div

ADDITIONAL RELIABILITY DATA: Contact your local ON Semiconductor Sales Representative or Bob Marquis <FC88FC@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Representative or Patrick Rousset <TTT252@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact Sales Representative or Patrick Rousset <TTT252@onsemi.com>

NOTIFICATION TYPE:
Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:
ON Semiconductor is pleased to announce the qualification and process certification of the 50V bipolar process in ON Semiconductor's wafer fabrication facility in the Czech Republic. ON Semiconductor's facility in the Czech Republic is a certified TS16949 and ISO-9000 factory qualified for the manufacturing of automotive products. The transfer program was announced in Initial PCN 12511, located at www.onsemi.com.

This is the Final PCN for the listed devices.

Three temperature electrical characterizations have been performed at the low, room, and high values across each device's full operating temperature range to insure there is no change to device functionality or data sheet electrical specifications. Qualification tests show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards. ON Semiconductor recommends that customers evaluate sample units in each associated application circuit to ensure there are no unexpected electrical incompatibilities.

Final Product/Process Change Notification #12511

RELIABILITY DATA SUMMARY:

Test	Conditions	Duration	Lots	Results
High Temp. Operating Life (HTOL)	Ta=+125c, Bias	1008 hrs	21 lots	0/1692
Early Life (ELFR)	TA=+125c, Bias	48 hrs	4 lots	0/3200
Temp. Cycle (TC)	-65c to +150c	500 cycles	15 lots	0/1155
Autoclave (AC)	+121c/15psig/100%RH	96 hrs	6 lots	0/462
Temp. humidity bias (THB)	+85c/85%RH	1008 hrs	3 lots	0/231
Power Temp. Cycle (PTC)	-40c to +125c	1000 cycles	1 lot	0/77
Wire bond pull strengh (BPS)	After TC	500 cycles	12 lots	0/60
Wire bond shear strengh (BS)	30 bonds from 5 units	N/A	1 lot	0/5

In addtition to the above tests, each qualification vehicle was subjected to the following tests in comparison to units manufactured at EG:

Test	Conditions	Duration	Lots	Results
ESD Testing	Human Body Model	N/A	1lot/device	Equivalent
	Machine Model	N/A	1lot/device	Equivalent
Dynamic Latch-up	6 units per lot	N/A	1lot/device	Equivalent

Three temperature electrical characterization of 3 lots/device showed no issues.

ELECTRICAL CHARACTERISTIC SUMMARY:
DEVICE PARAMETERS WILL CONTINUE TO MEET ALL DATA SHEET SPECIFICATIONS.
Characterization data is available upon request.

CHANGED PART IDENTIFICATION:
There will be no changes to standard device markings.
Normal assembly lot traceability codes will identify the wafer fab source.
Product shipped after the expiration date of this notice may be sourced with die produced in the Czech Republic facility.

Final Product/Process Change Notification #12511

AFFECTED DEVICE LIST (WITHOUT SPECIALS):

PART
CS8101YD8
CS8101YDR8
CS8101YDWF20
CS8101YDWFR20
CS8101YT5
CS8101YTHA5
CS8101YTVA5
CS8151CGN8
CS8151YDPS7
CS8151YDPSR7
CS8151YDWF16
CS8151YDWFR16
CS8151YNF16
CS8151YT7
CS8151YTHA7
CS8151YTVA7
CS8361YDPS7
CS8361YDPSR7
CS8361YDWF16
CS8361YDWFR16
CS9201YDF8
CS9201YDFR8
NCV7601P